

RFD10PO3-VB Datasheet

P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)			
- 30	0.056at V _{GS} = - 10 V	- 20	19 nC			
- 30	0.072 at V _{GS} = - 4.5 V	- 15	19110			

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Top View

TO-251 Drain Connected to

Drain-Tab

FEATURES

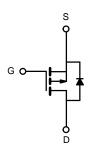
- Halogen-free
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested



RoHS

APPLICATIONS

- Load Switch
- · Notebook Adaptor Switch



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 1$	25 °C, unless othe	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	V	
Gate-Source Voltage		V_{GS}	± 20	v
	T _C = 25 °C		- 20	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 15	
Continuous Diain Curient (1) = 130 C)	T _A = 25 °C	I _D	-7.9 ^{a, b}	
	T _A = 70 °C		- 5.6 ^{a, b}	Α
Pulsed Drain Current	I _{DM}	- 60	A	
Continuous Source-Drain Diode Current	T _C = 25 °C	I-	- 20	
Continuous Source-Diain Diode Current	T _A = 25 °C	- I _S	- 7.9 ^{a, b}	
Avalanche Current	L = 0.1 mH	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	20	mJ
	T _C = 25 °C		20	
Maximum Dawar Dissination	T _C = 70 °C] _{B.}	15	W
Maximum Power Dissipation	T _A = 25 °C	P _D	2.7 ^{a, b}	VV
	T _A = 70 °C		1.7 ^{a, b}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	C/VV	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. Based on T_C = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static				I.		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 250 A		- 34		mV/
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		5.3		°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1.4		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 100	nA
Zana Oata Valtana Busin Oamani	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	
Zero Gate Voltage Drain Current		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 20			Α
	_	V _{GS} = - 10 V, I _D = - 6 A		0.056		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 4 A		0.072		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 6 A		28		S
Dynamic ^b						
Input Capacitance	C _{iss}			1150		pF
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		205		
Reverse Transfer Capacitance	C _{rss}			140		
Total Gate Charge		$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -6 \text{ A}$		27	43	
	Q _g V _{DS} = 13 V, V _{GS} = 10 V, 1 _D = 0 A		19	25	1	
Gate-Source Charge	Q_{gs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -6 \text{ A}$		6		nC
Gate-Drain Charge	Q_{gd}			12		
Gate Resistance	R_g	f = 1 MHz	0.5	2.2	4.4	Ω
Turn-On Delay Time	t _{d(on)}			13	25	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 1.5 \Omega$		12	24	1
Turn-Off DelayTime	t _{d(off)}	$I_{D} \cong -10 \text{ A}, V_{GEN} = -10 \text{ V}, R_{g} = 1 \Omega$		40	70	
Fall Time	t _f	Ţ		9	18	
Turn-On Delay Time	t _{d(on)}			48	80	ns
Rise Time	\$ 7			92	160	
Turn-Off DelayTime	t _{d(off)}	$I_{D} \cong -6 \text{ A}, \ V_{GEN} = -4.5 \text{ V}, R_{g} = 1 \Omega$		34	60	1
Fall Time	t _f			19	35	1
Drain-Source Body Diode Characteris	stics					
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 4.1	^
Pulse Diode Forward Current	I _{SM}				- 60	A
Body Diode Voltage	V _{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.75	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			27	45	ns
Body Diode Reverse Recovery Charge	Q _{rr}	L CA dl/dt 100 A/:- T 0500		16	27	nC
Reverse Recovery Fall Time	t _a	$I_F = -6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		12		ns
Reverse Recovery Rise Time	t _b			15		

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

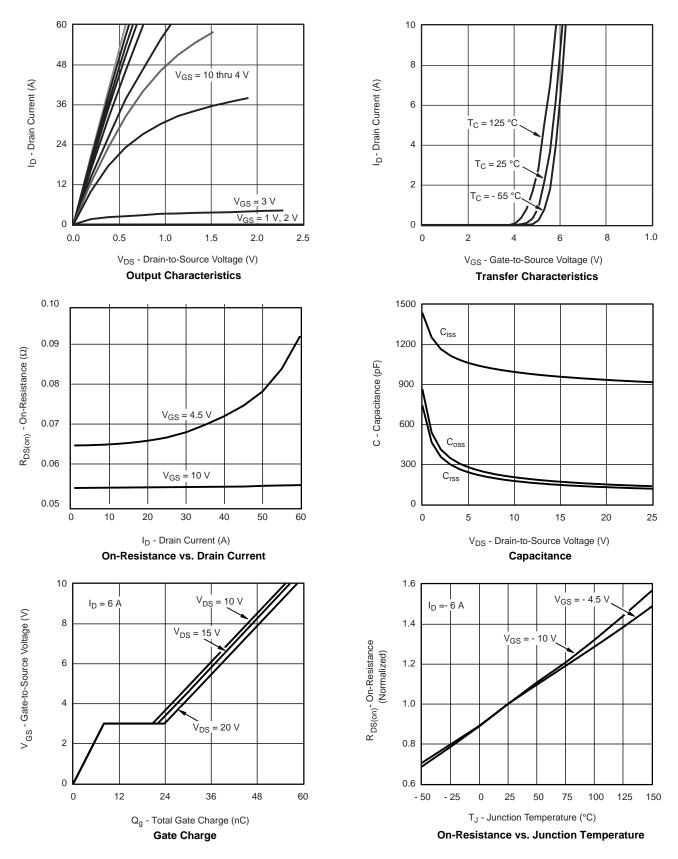
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a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

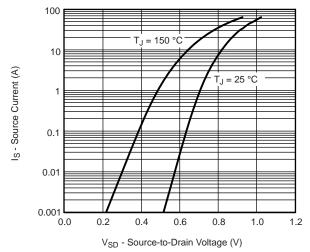


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

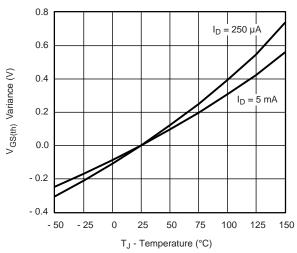




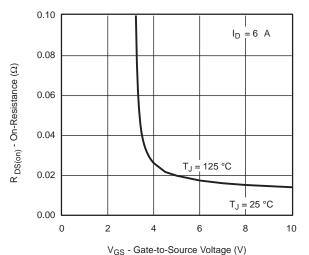
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Source-Drain Diode Forward Voltage



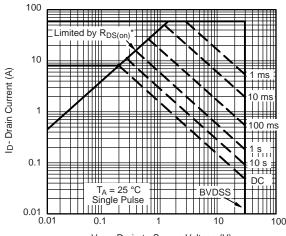
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient

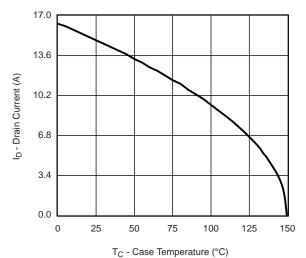


 V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

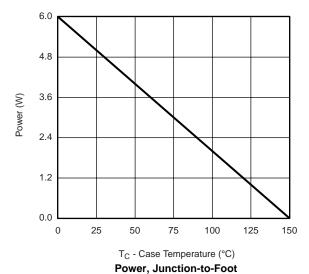
Safe Operating Area

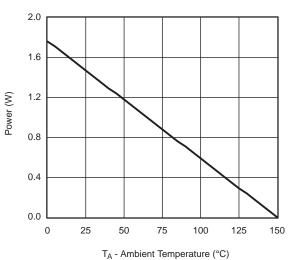


MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*





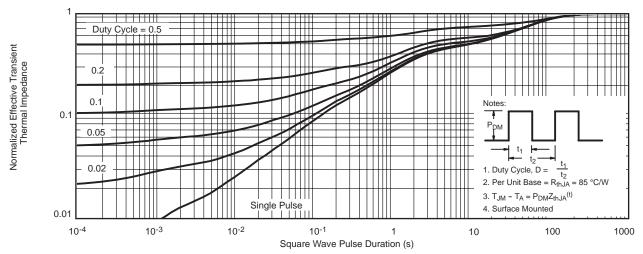
Power Derating, Junction-to-Ambient

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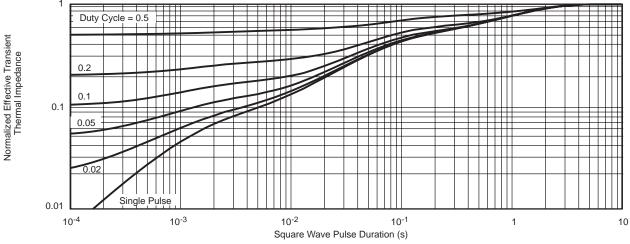
^{*} The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



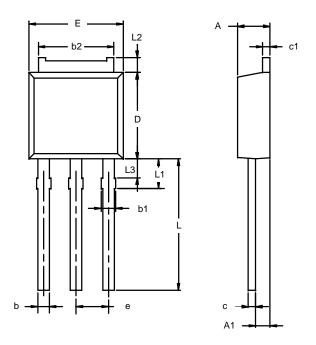
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



TO-251AA



Note: Dimension L3 is for reference only.

	MILLIM	IETERS	INC	HES
Dim	Min	Max	Min	Max
Α	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
С	0.46	0.58	0.018	0.023
с1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
E	6.48	6.73	0.255	0.265
е	2.28 BSC		0.090	BSC
L	3.89	9.53	0.153	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060

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